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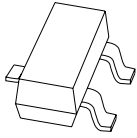
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Kind regards,

Team Nexperia



# PDTB113ET

PNP 500 mA, 50 V resistor-equipped transistor;  
R1 = 1 k $\Omega$ , R2 = 1 k $\Omega$

Rev. 3 — 14 September 2010

Product data sheet

## 1. Product profile

### 1.1 General description

500 mA PNP Resistor-Equipped Transistor (RET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

NPN complement: PDTD113ET.

### 1.2 Features and benefits

- 500 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs
- $\pm 10\%$  resistor ratio tolerance
- AEC-Q101 qualified

### 1.3 Applications

- Digital application in automotive and industrial segments
- Control of IC inputs
- Cost-saving alternative for BC807 series in digital applications
- Switching loads

### 1.4 Quick reference data

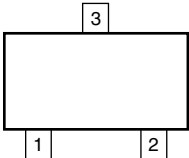
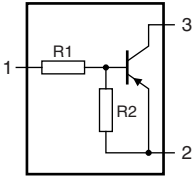
Table 1. Quick reference data

| Symbol           | Parameter                 | Conditions | Min | Typ | Max  | Unit       |
|------------------|---------------------------|------------|-----|-----|------|------------|
| V <sub>CEO</sub> | collector-emitter voltage | open base  | -   | -   | -50  | V          |
| I <sub>O</sub>   | output current            |            | -   | -   | -500 | mA         |
| R1               | bias resistor 1 (input)   |            | 0.7 | 1.0 | 1.3  | k $\Omega$ |
| R2/R1            | bias resistor ratio       |            | 0.9 | 1.0 | 1.1  |            |



## 2. Pinning information

Table 2. Pinning

| Pin | Description        | Simplified outline                                                                              | Graphic symbol                                                                                |
|-----|--------------------|-------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------|
| 1   | input (base)       | <br>006aaa144 | <br>sym003 |
| 2   | GND (emitter)      |                                                                                                 |                                                                                               |
| 3   | output (collector) |                                                                                                 |                                                                                               |

## 3. Ordering information

Table 3. Ordering information

| Type number | Package |                                          |         |
|-------------|---------|------------------------------------------|---------|
|             | Name    | Description                              | Version |
| PDTB113ET   | -       | plastic surface-mounted package; 3 leads | SOT23   |

## 4. Marking

Table 4. Marking codes

| Type number | Marking code <sup>[1]</sup> |
|-------------|-----------------------------|
| PDTB113ET   | *7U                         |

- [1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

## 5. Limiting values

Table 5. Limiting values

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol    | Parameter                 | Conditions     | Min | Max  | Unit |
|-----------|---------------------------|----------------|-----|------|------|
| $V_{CBO}$ | collector-base voltage    | open emitter   | -   | -50  | V    |
| $V_{CEO}$ | collector-emitter voltage | open base      | -   | -50  | V    |
| $V_{EBO}$ | emitter-base voltage      | open collector | -   | -10  | V    |
| $V_I$     | input voltage             |                |     |      |      |
|           | positive                  |                | -   | +10  | V    |
|           | negative                  |                | -   | -10  | V    |
| $I_O$     | output current            |                | -   | -500 | mA   |

**Table 5. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol    | Parameter               | Conditions                  | Min   | Max  | Unit |
|-----------|-------------------------|-----------------------------|-------|------|------|
| $P_{tot}$ | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | [1] - | 250  | mW   |
| $T_j$     | junction temperature    |                             | -     | 150  | °C   |
| $T_{amb}$ | ambient temperature     |                             | -65   | +150 | °C   |
| $T_{stg}$ | storage temperature     |                             | -65   | +150 | °C   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

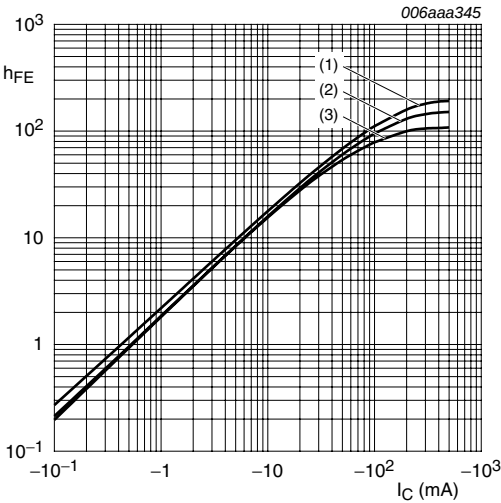
| Symbol        | Parameter                                   | Conditions  | Min   | Typ | Max | Unit |
|---------------|---------------------------------------------|-------------|-------|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] - | -   | 500 | K/W  |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

## 7. Characteristics

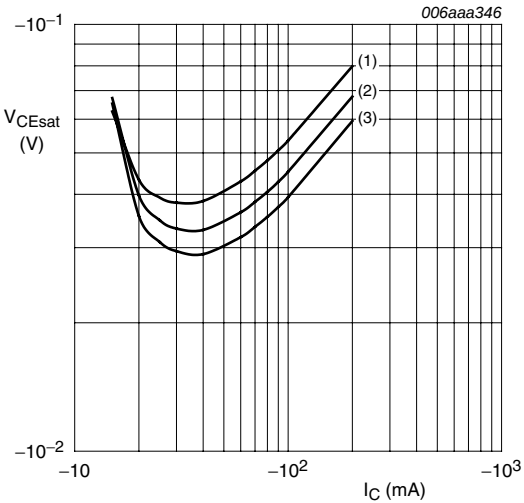
**Table 7. Characteristics** $T_{amb} = 25\text{ °C}$  unless otherwise specified.

| Symbol       | Parameter                            | Conditions                                                                    | Min  | Typ  | Max  | Unit |
|--------------|--------------------------------------|-------------------------------------------------------------------------------|------|------|------|------|
| $I_{CBO}$    | collector-base cut-off current       | $V_{CB} = -40\text{ V}; I_E = 0\text{ A}$                                     | -    | -    | -100 | nA   |
|              |                                      | $V_{CB} = -50\text{ V}; I_E = 0\text{ A}$                                     | -    | -    | -100 | nA   |
| $I_{CEO}$    | collector-emitter cut-off current    | $V_{CE} = -50\text{ V}; I_B = 0\text{ A}$                                     | -    | -    | -0.5 | μA   |
| $I_{EBO}$    | emitter-base cut-off current         | $V_{EB} = -5\text{ V}; I_C = 0\text{ A}$                                      | -    | -    | -4.0 | mA   |
| $h_{FE}$     | DC current gain                      | $V_{CE} = -5\text{ V};$<br>$I_C = -50\text{ mA}$                              | 33   | -    | -    |      |
| $V_{CEsat}$  | collector-emitter saturation voltage | $I_C = -50\text{ mA};$<br>$I_B = -2.5\text{ mA}$                              | -    | -    | -0.3 | V    |
| $V_{I(off)}$ | off-state input voltage              | $V_{CE} = -5\text{ V};$<br>$I_C = -100\text{ μA}$                             | -0.6 | -1.1 | -1.5 | V    |
| $V_{I(on)}$  | on-state input voltage               | $V_{CE} = -0.3\text{ V};$<br>$I_C = -20\text{ mA}$                            | -1.0 | -1.4 | -1.8 | V    |
| R1           | bias resistor 1 (input)              |                                                                               | 0.7  | 1.0  | 1.3  | kΩ   |
| R2/R1        | bias resistor ratio                  |                                                                               | 0.9  | 1.0  | 1.1  |      |
| $C_c$        | collector capacitance                | $V_{CB} = -10\text{ V};$<br>$I_E = I_e = 0\text{ A};$<br>$f = 100\text{ MHz}$ | -    | 11   | -    | pF   |



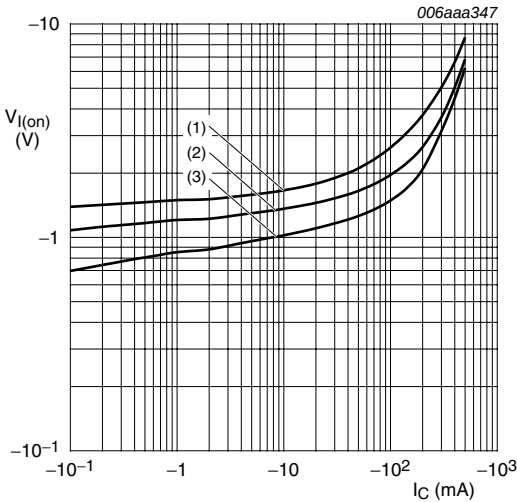
- $V_{CE} = -5\text{ V}$
- (1)  $T_{amb} = 100^\circ\text{C}$
  - (2)  $T_{amb} = 25^\circ\text{C}$
  - (3)  $T_{amb} = -40^\circ\text{C}$

Fig 1. DC current gain as a function of collector current; typical values



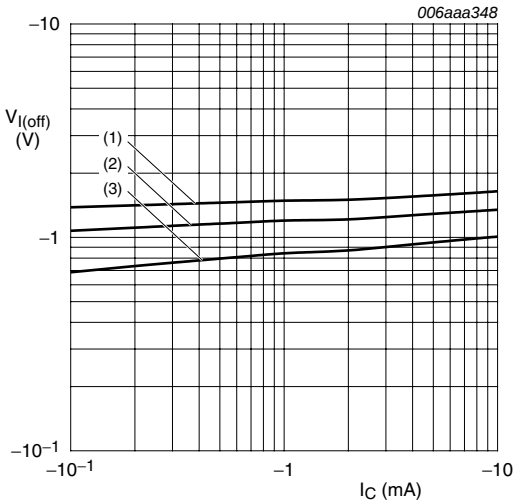
- $I_C/I_B = 20$
- (1)  $T_{amb} = 100^\circ\text{C}$
  - (2)  $T_{amb} = 25^\circ\text{C}$
  - (3)  $T_{amb} = -40^\circ\text{C}$

Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values



- $V_{CE} = -0.3\text{ V}$
- (1)  $T_{amb} = -40^\circ\text{C}$
  - (2)  $T_{amb} = 25^\circ\text{C}$
  - (3)  $T_{amb} = 100^\circ\text{C}$

Fig 3. On-state input voltage as a function of collector current; typical values



- $V_{CE} = -5\text{ V}$
- (1)  $T_{amb} = -40^\circ\text{C}$
  - (2)  $T_{amb} = 25^\circ\text{C}$
  - (3)  $T_{amb} = 100^\circ\text{C}$

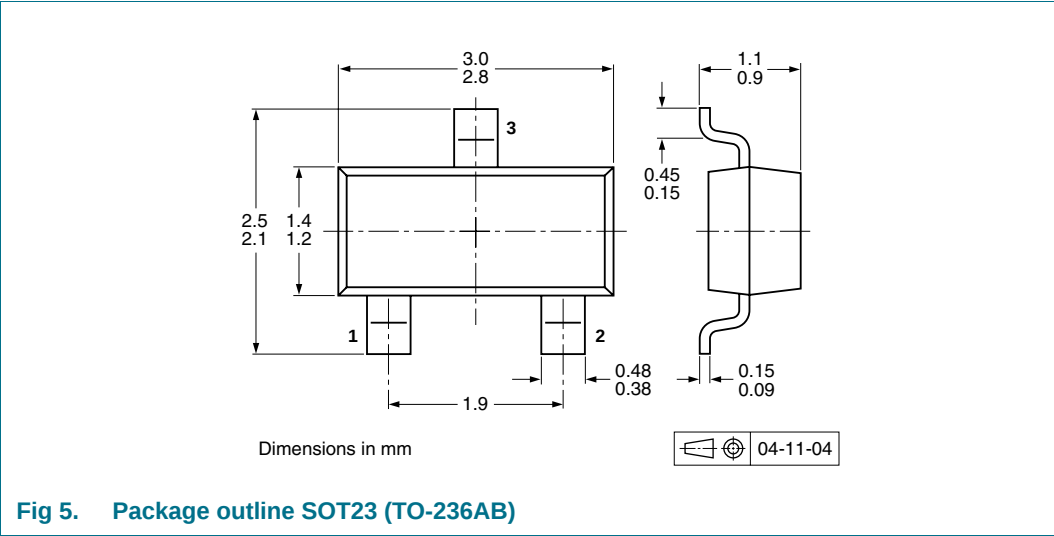
Fig 4. Off-state input voltage as a function of collector current; typical values

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

**Table 8. Packing methods**  
The indicated -xxx are the last three digits of the 12NC ordering code.[\[1\]](#)

| Type number | Package | Description                    | Packing quantity |       |
|-------------|---------|--------------------------------|------------------|-------|
|             |         |                                | 3000             | 10000 |
| PDTB113ET   | SOT23   | 4 mm pitch, 8 mm tape and reel | -215             | -235  |

[1] For further information and the availability of packing methods, see [Section 14](#).



## 12. Revision history

Table 9. Revision history

| Document ID    | Release date                                                                                                                                                                                                                                                                                                                                                                                | Data sheet status  | Change notice | Supersedes     |
|----------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------|---------------|----------------|
| PDTB113ET v.3  | 20100914                                                                                                                                                                                                                                                                                                                                                                                    | Product data sheet | -             | PDTB113E_SER_2 |
| Modifications: | <ul style="list-style-type: none"><li>Type numbers PDTB113EK and PDTB113ES deleted.</li><li><a href="#">Table 7 "Characteristics"</a>: unit for <math>V_{CEsat}</math> changed from mV to V.</li><li><a href="#">Section 8 "Test information"</a>: added.</li><li><a href="#">Section 11 "Soldering"</a>: added.</li><li><a href="#">Section 13 "Legal information"</a>: updated.</li></ul> |                    |               |                |
| PDTB113E_SER_2 | 20091116                                                                                                                                                                                                                                                                                                                                                                                    | Product data sheet | -             | PDTB113E_SER_1 |
| PDTB113E_SER_1 | 20050427                                                                                                                                                                                                                                                                                                                                                                                    | Product data sheet | -             | -              |

## 13. Legal information

### 13.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition                                                                            |
|-----------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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